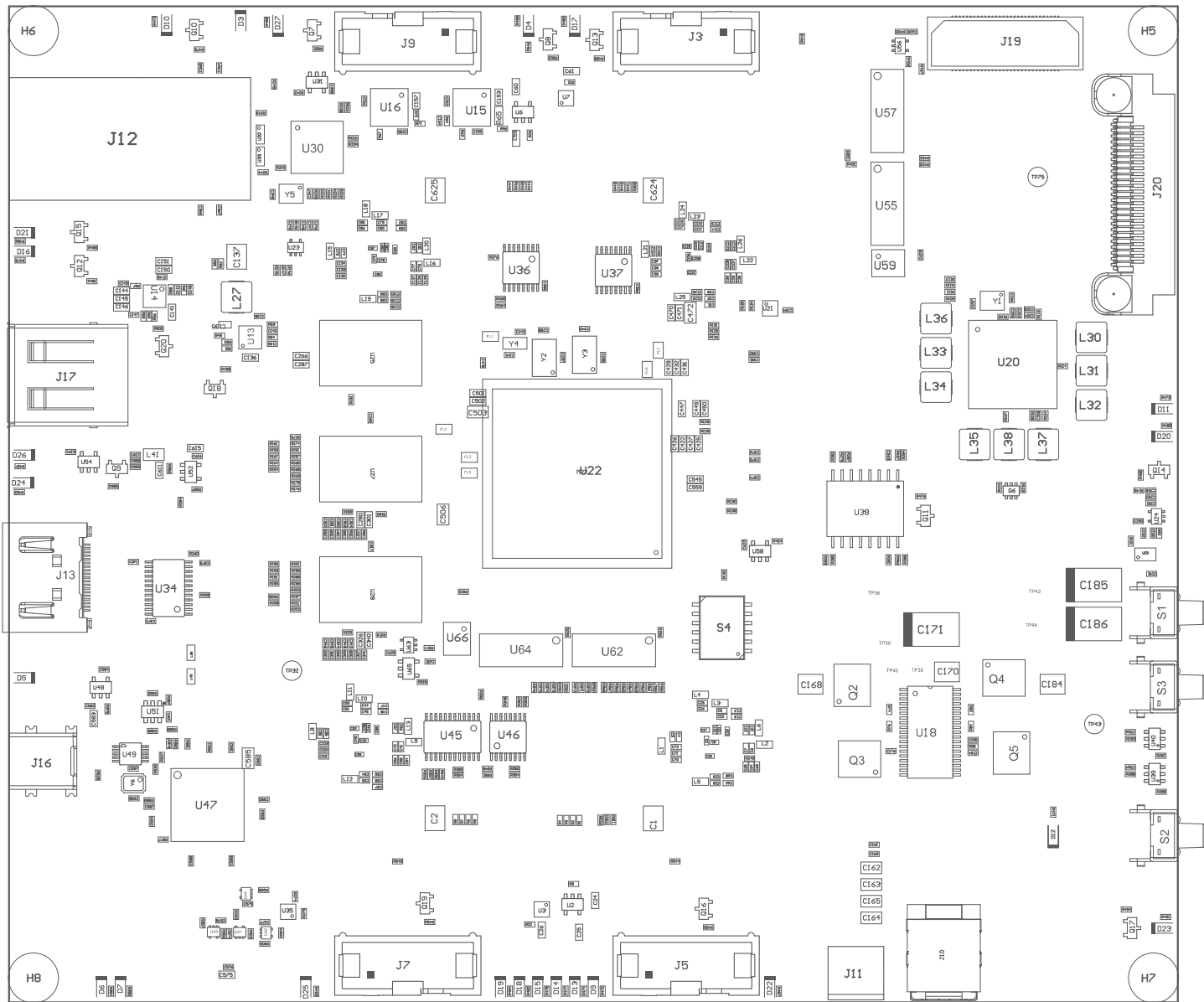


Z22 ■ These assemblies are ESD sensitive, ESD precautions shall be observed.  
 Z23 ■ These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.  
 Z24 ■ These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.  
 Z25 ■ INDICATION FOR COMPONENTS D\* (WITH 2 PINS) ARE GIVEN AT THEIR CATHODE SIDE.  
 Z26 ■ MPI must be soldered down to the Top Layer of PCB.  
 Z27 ■ Refer to Test Procedure Document for installing uSD, H9, and SSD Drive



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.  
 ASSEMBLY VARIANT: 001

PCB VIEWED FROM TOP SIDE	BOARD #: PROC055	REV: B	SUN REV: Not In VersionControl
	TID #: N/A		
PLOT NAME = Top Assembly Drawing	GENERATED : 9/21/2021	3:20:42 PM	TEXAS INSTRUMENTS



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.  
 ASSEMBLY VARIANT: 001

PCB VIEWED FROM BOTTOM SIDE	BOARD #: PROC055	REV: B	SUN REV: Not In VersionControl
	TID #: N/A		
PLOT NAME = Bottom Assembly Drawing	GENERATED : 9/21/2021	3: 20:42 PM	TEXAS INSTRUMENTS

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